

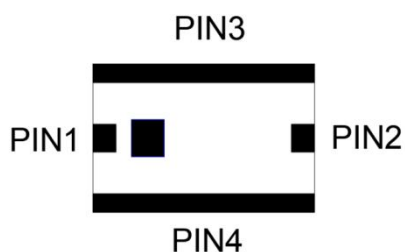
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

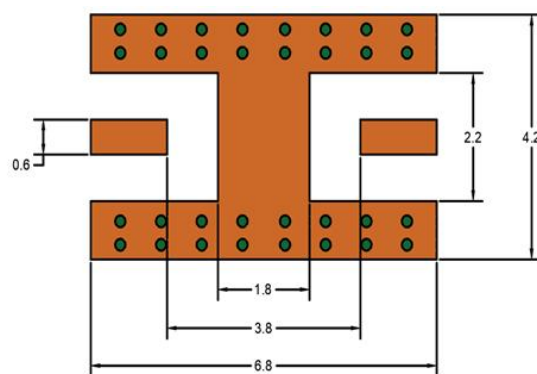
NO.	Parameter		SPEC
1	Frequency (MHz)		725~775
2	Insertion Loss (dB) @25℃		≤3.5
3	Ripple (dB)		≤1.0
4	VSWR(In BW)		≤1.8
5	Attenuation	1~450MHz	≥26dB
		1050~3500MHz	≥26dB
6	In/Output Impedance (Ω)		50
Operating & Storage Condition (Component)			
Operation Temperature Range: -40℃ ~ +85℃			
Storage Temperature Range: -40℃~ +85℃			
Storage Condition before Soldering (Included packaging material)			
Storage Temperature Range: +5 ~ +40 ℃			
Humidity: 30 to 70% relative humidity			

Construction



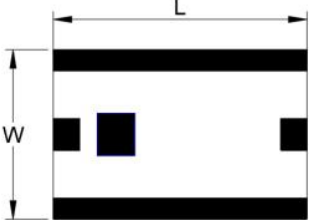
PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

Mounting Considerations

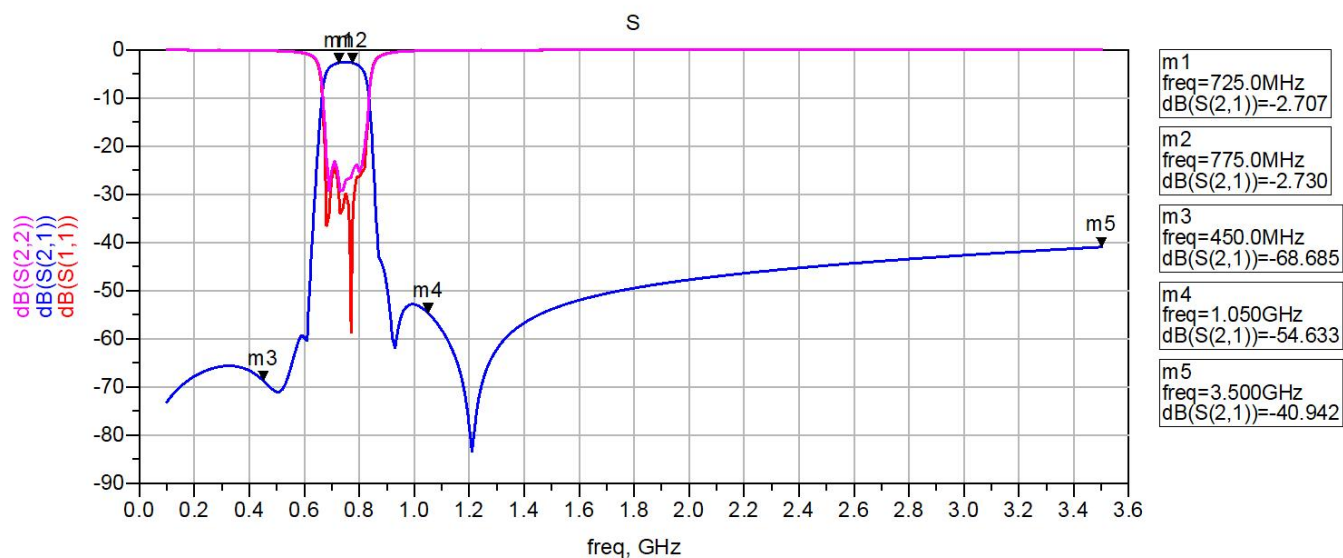


Unit: mm

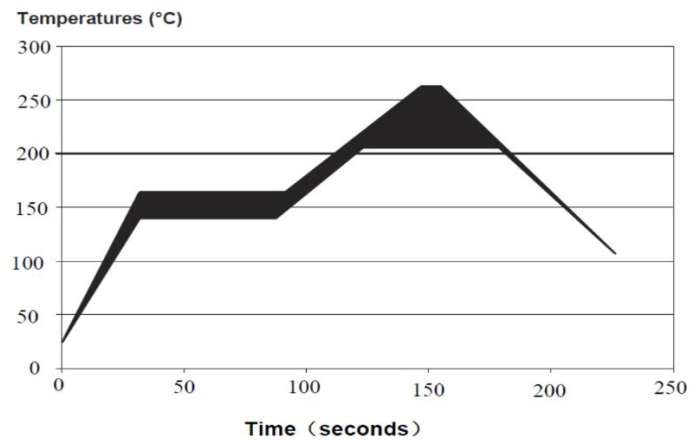
Dimensions

Figure	Symbol	Dimension (mm)
TOP VIEW  BOTTOM VIEW  SIDE VIEW 	L	5.00 ± 0.20
	W	3.20 ± 0.20
	T	1.50 ± 0.20
	A	0.60 ± 0.10
	B	0.50 ± 0.10
	C	0.40 ± 0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.